


**NOTES**

- MATERIALS:**  
LEAD FRAME: COPPER 194FH, THK = 0.203±0.008  
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QPTECHNOLOGIES FOR DETAILS.
- FINISH:**  
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 200 TO 300 MICRONS (2.5um-7.6um) THICK.  
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICRONS (1um-2um) THICK).  
BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)
- PACKAGE MISMATCH:** BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.
- UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.**
- PACKAGE CONFORMS TO JEDEC MO-220**

**PROPRIETARY AND CONFIDENTIAL**  
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		UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: ANGULAR: ±0.5 degree .X = ±0.76 .XX: ±0.25 .XXX = ±0.13 .XXXX = ±0.01		DRAWN	D. Abbe	7/28/11	 <b>TITLE:</b> QP-QFN8-3MM-0.65MM
		MATERIAL SEE NOTE 1		CHECKED	S. Swen	7/28/11	
		FINISH SEE NOTE 2		ENG APPR.	S. Swen	7/28/11	
NEXT ASSY		USED ON		COMMENTS:			
APPLICATION		DO NOT SCALE DRAWING		SIZE		DWG. NO.	REV
				<b>B</b>		<b>500368</b>	<b>A</b>
				SCALE: 16:1		WEIGHT:	SHEET 1 OF 1

